

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.16
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.2
	Lead alloy	Lead (Pb)	7439-92-1	0.39	95.5	7.83
<b>Subtotal</b>				<b>0.41</b>	<b>100</b>	<b>8.19</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.75
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01	100.0	0.28
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.74	100.0	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.43
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.42
	Copper alloy	Copper (Cu)	7440-50-8	70.05	99.67	1412.32
	Copper alloy	Silver (Ag)	7440-22-4	0.14	0.2	2.83
	<b>Subtotal</b>				<b>70.28</b>	<b>100</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.85	6.5	37.38
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.56	16.0	92
	Filler	Silica fused	60676-86-0	20.25	71.0	408.25
	Flame retardant	Metal hydroxide		1.85	6.5	37.38
	<b>Subtotal</b>				<b>28.51</b>	<b>100</b>
<b>Total</b>				<b>99.99</b>	<b>100</b>	<b>2016.23</b>

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